Abstract

SEMICONDUCTOR DEVICE AND METHOD OF FABRICATION THEREOF, SEMICONDUCTOR MODULE, CIRCUIT BOARD AND ELECTRONIC EQUIPMENT

A method of fabricating a semiconductor device comprises the steps of: preparing a tape carrier 10 on which is formed lines of a plurality of bonding portions 14 across the width thereof, in a pattern that repeats along the length thereof, and winding the tape carrier 10 on a reel 24; providing an anisotropic conductive film 30 on at least the bonding portions 14; mounting a surface 36 having electodes 34 of semiconductor chips 32 on the anisotropic conductive film 30; applying pressure to the semiconductor chips 32 in the direction of the bonding portions 14, to connect the bonding portions 14 electrically to the electrodes 34; forming external electrodes 38 to the tape carrier 10; and punching out the tape carrier 10 into individual units for each semiconductor chip 32.

Fig. 1

ABSTRACT

A method of fabricating a semiconductor device comprises the steps of: preparing a tape carrier 10 on which is formed lines of a plurality of bonding portions 14 across the width thereof, in a pattern that repeats along the length thereof, and winding the tape carrier 10 on a reel 24; providing an anisotropic conductive film 30 on at least the bonding portions 14; mounting a surface 36 having electrodes 34 of semiconductor chips 32 on the anisotropic conductive film 30; applying pressure to the semiconductor chips 32 in the direction of the bonding portions 14, to connect the bonding portions 14 electrically to the electrodes 34; forming external electrodes 38 in the tape carrier 10; and punching out the tape carrier 10 into individual units for each semiconductor chip 32.